



ZXMS6004DT8 60V N-CHANNEL SELF PROTECTED ENHANCEMENT MODE INTELLIFETTM MOSFET

SUMMARY

Continuous drain source voltage 60 V

On-state resistance 500 m Ω

Nominal load current $(V_{IN} = 5V)$ 1.2 A

Clamping Energy 210 mJ

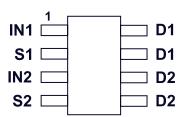


SM8 Package

DESCRIPTION

The ZXMS6004DT8 is a dual self protected low side MOSFET with logic level input. It integrates over-temperature, over-current, over-voltage (active clamp) and ESD protected logic level functionality independently per channel. The ZXMS6004DT8 is ideal as a general purpose switch driven from 3.3V or 5V microcontrollers in harsh environments where standard

MOSFETs are not rugged enough.



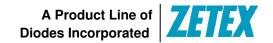
FEATURES

- Compact dual package
- Low input current
- Logic Level Input (3.3V and 5V)
- Short circuit protection with auto restart
- Over voltage protection (active clamp)
- Thermal shutdown with auto restart
- Over-current protection
- Input Protection (ESD)
- · High continuous current rating

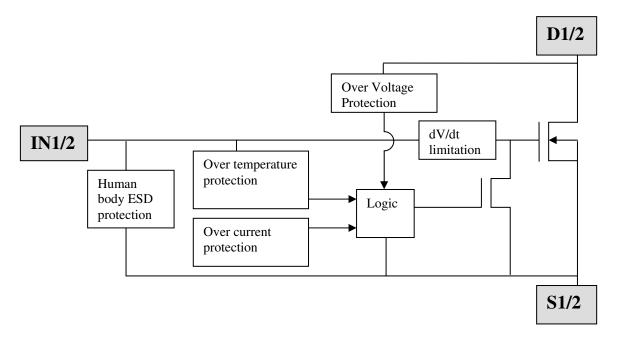
ORDERING INFORMATION

DEVICE	PART	REEL SIZE	TAPE WIDTH	QUANTITY PER
	MARK	(inches)	(mm)	REEL
ZXMS6004DT8TA	ZXMS 6004D	7	12 embossed	1,000 units





FUNCTIONAL BLOCK DIAGRAM



APPLICATIONS AND INFORMATION

- Two completely isolated independent channels
- Especially suited for loads with a high in-rush current such as lamps and motors.
- All types of resistive, inductive and capacitive loads in switching applications.
- μC compatible power switch for 12V and 24V DC applications.
- Automotive rated.
- Replaces electromechanical relays and discrete circuits.
- Linear Mode capability the current-limiting protection circuitry is designed to de-activate
 at low V_{DS} to minimise on state power dissipation. The maximum DC operating current is
 therefore determined by the thermal capability of the package/board combination, rather
 than by the protection circuitry. This does not compromise the product's ability to selfprotect at low V_{DS}.





ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Continuous Drain-Source Voltage	V_{DS}	60	V
Drain-Source Voltage for short circuit protection	$V_{DS(SC)}$	36	V
Continuous Input Voltage	V _{IN}	-0.5 +6	V
Continuous Input Current	I _{IN}		mA
-0.2V≤V _{IN} ≤6V		No limit	
V_{IN} <-0.2V or V_{IN} >6V		I _{IN} ≤2	
Operating Temperature Range	T _j ,	-40 to +150	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C
Power Dissipation at T _A =25°C (a)(d)	P_D	1.16	W
Linear Derating Factor		9.28	mW/°C
Power Dissipation at T _A =25°C (a)(e)	P_D	1.67	W
Linear Derating Factor		13.3	mW/°C
Power Dissipation at T _A =25°C (b)(d)	P_D	2.13	W
Linear Derating Factor		17	mW/°C
Pulsed Drain Current @ V _{IN} =3.3V (c)	I _{DM}	2	Α
Pulsed Drain Current @ V _{IN} =5V (c)	I _{DM}	2.5	Α
Continuous Source Current (Body Diode) (a)	I _S	1	Α
Pulsed Source Current (Body Diode) (c)	I _{SM}	5	А
Unclamped single pulse inductive energy, Tj=25°C, I_D =0.5A, V_{DD} =24V	E _{AS}	210	mJ
Electrostatic Discharge (Human Body Model)	V_{ESD}	4000	V
Charged Device Model	V_{CDM}	1000	V

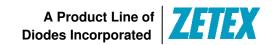
THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(d)	$R_{\theta JA}$	108	°C/W
Junction to Ambient (a)(e)	$R_{\theta JA}$	75	°C/W
Junction to Ambient (b)(d)	$R_{\theta JA}$	58.7	°C/W
Junction to Case (f)	$R_{ heta JC}$	26.5	°C/W

NOTES

- (a) For a dual device surface mounted on a 25mm x 25mm FR4 PCB single sided 1oz weight copper split down the middle on 1.6mm FR4 board, in still air conditions.
- (b) For a dual device surface mounted on FR4 PCB measured at t ≤ 10sec
- (c) Repetitive rating 25mm x 25mm FR4 PCB, D=0.02 pulse width=300μs pulse width limited by junction temperature. Refer to transient Thermal Impedance Graph.
- (d) For a dual device with one active die.
- (e) For dual device with 2 active die running at equal power.
- (f) Thermal resistance from junction to solder-point (at the end of the drain lead)



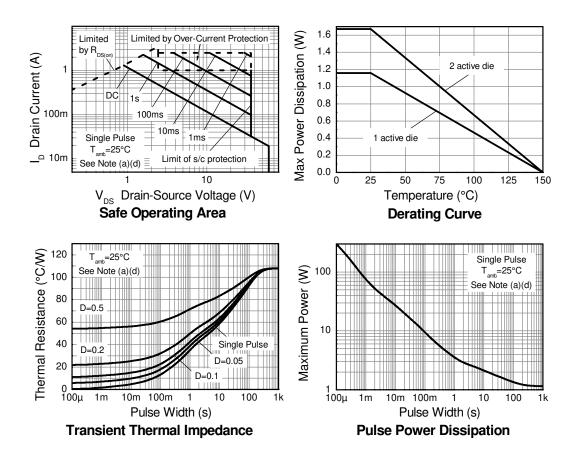


RECOMMENDED OPERATING CONDITIONS

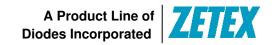
The ZXMS6004DT8 is optimised for use with μC operating from 3.3V and 5V supplies.

Symbol	Description	Min	Max	Units
V_{IN}	Input voltage range	0	5.5	V
T_A	Ambient temperature range	-40	125	°C
V_{IH}	High level input voltage for MOSFET to be on	3	5.5	V
V _{IL}	Low level input voltage for MOSFET to be off	0	0.7	V
V_P	Peripheral supply voltage (voltage to which load is referred)	0	36	V

CHARACTERISTICS







ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS	
Static Characteristics							
Drain-Source Clamp Voltage	$V_{DS(AZ)}$	60	65	70	V	I _D =10mA	
Off state Drain Current	I _{DSS}			500	nA	$V_{DS}=12V, V_{IN}=0V$	
Off state Drain Current	I _{DSS}			1	uA	V_{DS} =36V, V_{IN} =0V	
Input Threshold Voltage	$V_{IN(th)}$	0.7	1	1.5	V	$V_{DS}=V_{GS}$, $I_{D}=1$ mA	
Input Current	I _{IN}		60	100	μΑ	V _{IN} =+3V	
Input Current	I _{IN}		120	200	μА	$V_{IN}=+5V$	
Input Current while over temperature active				220	μΑ	V _{IN} =+5V	
Static Drain-Source On-State Resistance	R _{DS(on)}		400	600	mΩ	$V_{IN} = +3V, I_D = 0.5A$	
Static Drain-Source On-State Resistance	R _{DS(on)}		350	500	mΩ	$V_{IN} = +5V, I_D = 0.5A$	
Continuous Drain Current (a)(e)	I _D	0.9			Α	V _{IN} =3V; T _A =25°C	
Continuous Drain Current (a)(e)	I _D	1.0			Α	V _{IN} =5V; T _A =25°C	
Continuous Drain Current (a)(d)	I _D	1.1			Α	V _{IN} =3V; T _A =25°C	
Continuous Drain Current (a)(d)	I _D	1.2			Α	V _{IN} =5V; T _A =25°C	
Current Limit (g)	I _{D(LIM)}	0.7	1.7		Α	$V_{IN}=+3V$,	
Current Limit (g)	I _{D(LIM)}	1	2.2		Α	V _{IN} =+5V	
Dynamic Characteristics							
Turn On Delay Time	$t_{d(on)}$		5		μS	$V_{DD}=12V, I_{D}=0.5A,$	
Rise time	t _r		10		μS	V _{GS} =5V	
Turn Off Delay Time	$t_{d(off)}$		45		μS		
Fall Time	f _f		15		μS		

Notes:

(g) The drain current is restricted only when the device is in saturation (see graph 'typical output characteristic'). This allows the device to be used in the fully on state without interference from the current limit. The device is fully protected at all drain currents, as the low power dissipation generated outside saturation makes current limit unnecessary.



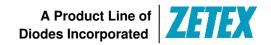


PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS
Over-temperature Protection						
Thermal Overload Trip Temperature (h)	T_{JT}	150	175		°C	
Thermal hysteresis (h)			10		°C	

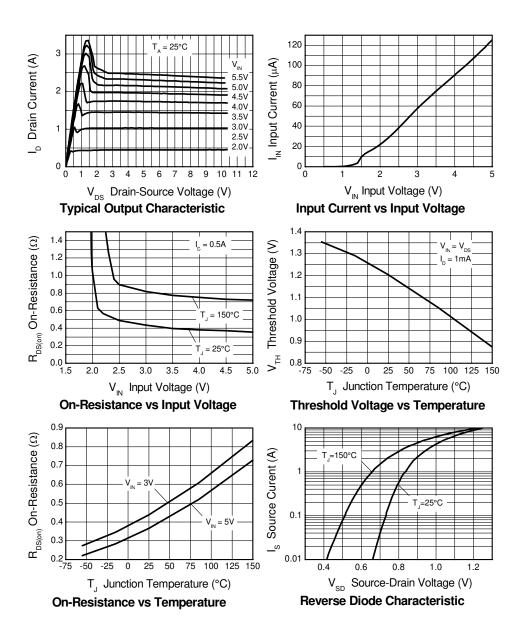
Note:

(h) Over-temperature protection is designed to prevent device destruction under fault conditions. Fault conditions are considered as "outside" normal operating range, so this part is not designed to withstand over-temperature for extended periods..

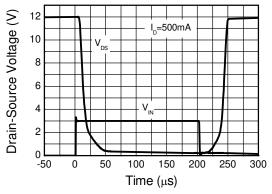


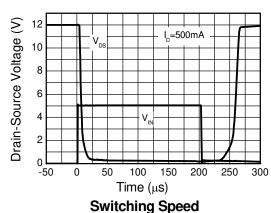


TYPICAL CHARACTERISTICS

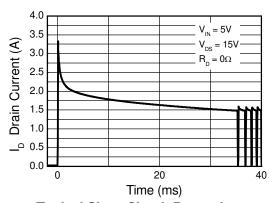






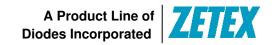


Switching Speed



Typical Short Circuit Protection





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